



To the Honorable Commissioner of Patents and

100977776

Original documents or copy thereof

1. Name of Conveying Part(ies):

Adam D. Selsley

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Internal Address: _____

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83706

Additional name(s) of conveying party(ies) attached? Yes No

Additional names(s) & address(es) attached: Yes No

3. Nature of conveyance:

2-18-99

- Assignment Security Agreement
- Merger Change of Name
- Other _____

Execution Date: February 12, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: February 12, 1999

A. Patent Application No.(s):

B. Patent No.(s)

Additional numbers attached: Yes No

Additional numbers attached: Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mark S. Matkin

Internal Address: Wells, St. John, Roberts,

Gregory & Matkin P.S.

Street Address: 601 W. First Avenue, Ste. 1300

City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved. 1

7. Total fee (37 CFR 3.41) \$ 40

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number

23-0925

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark S. Matkin

Name of Person Signing

Signature

2-18-99

Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 4

OMB No. 0651-0011 (exp. 9/94)

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EL169837799

PATENT

REEL: 9788 FRAME: 0929

1 PATENT ASSIGNMENT

2 PARTIES TO THE ASSIGNMENT:

3 INVENTOR:

4 Adam D. Selsley

5 ASSIGNEE:

6 Micron Technology, Inc.
7 Corporation of the State of Delaware
8 8000 South Federal Way
9 Boise, Idaho 83706-9632

10 BACKGROUND OF THIS ASSIGNMENT:

11 INVENTOR has conceived certain new and useful inventions
12 disclosed in a United States patent application titled **Method Of Forming**
13 **A Conductive Connection On A Substrate Between A First Region And**
14 **A Second Region, Method Of Forming A Conductive Interface To Be**
15 **Received Between A First Region And A Second Region, Method Of**
16 **Forming A Conductive Contact, And Method Of Forming A Conductive**
17 **Line.**

18 MICRON TECHNOLOGY, INC. desires to acquire the entire right,
19 title and interest in said inventions and with respect to any Letters
20 Patent that may be granted with respect to the inventions in both the
21 United States and in all foreign countries.

22 THE PARTIES AGREE AS FOLLOWS:

23 In consideration of good and valuable consideration, the receipt
24 sufficiency and adequacy of which is hereby acknowledged, INVENTOR
hereby sells, assigns and transfers to MICRON TECHNOLOGY, INC.

1 the entire right and interest in the above-identified application executed
2 concurrently with this assignment and to any reissues, renewals, divisions
3 or continuations thereof, and hereby authorizes the Commissioner of
4 Patents and Trademarks to issue such Letters Patent to MICRON
5 TECHNOLOGY, INC. for the sole use of MICRON TECHNOLOGY,
6 INC., its successors or assigns.

7 INVENTOR further agrees to execute, at the request and expense
8 of MICRON TECHNOLOGY, INC. such other formal documents as may
9 be required to fully convey the interest transferred herein and will
10 similarly execute any application papers required for the filing of any
11 division, continuation, renewal or reissue of the patent application or
12 resulting Letters Patent; and will generally do everything necessary or
13 desirable to obtain and enforce proper protection for the invention
14 assigned hereby.

15 INVENTOR further assigns to MICRON TECHNOLOGY, INC. the
16 whole right, title and interest in the inventions disclosed in the
17 application throughout all countries foreign to the United States.
18 MICRON TECHNOLOGY, INC. is hereby authorized to apply for
19 patents relating to the inventions in its own name in countries where
20 such procedure is proper; to claim the benefit of the International
21 Convention; to file and prosecute International Applications relating to
22 the inventions under the Patent Cooperation Treaty; and to file and
23 prosecute applications relating to the inventions under the European
24 Patent Convention. INVENTOR agrees to execute applications relating

1 to the inventions in those countries and under those conventions where
2 it is necessary that the same be executed by the inventor, and to
3 execute assignments of such applications and the resulting Letters Patent
4 to MICRON TECHNOLOGY, INC. as well as all other necessary papers
5 in relation to such applications and Letters Patent.

6 INVENTOR further warrants and covenants that no assignment,
7 grant, mortgage, license or other agreement affecting the rights and
8 property herein conveyed has been or will be made to others by the
9 undersigned, and that the full rights to convey the same as herein
10 expressed is possessed by the undersigned.

11 To be binding on the heirs, assigns, representatives and successors
12 of the undersigned and extend to the successors, assigns and nominees
13 of the Assignees

14 (Signature) *Adam D. Selsley* Date: 2/12/99
15 Adam D. Selsley

16 State of Idaho)
17 County of Ada) ss.

18 BEFORE ME, this 12 day of February 1999
19 personally appeared the above-named inventor, to me known to be the
20 person who is described in and who executed the foregoing assignment
instrument and acknowledged to me that he/she executed the same of
his/her own free will for the purpose therein expressed.



21
22
23 *Lisa Boyer*
Notary or Consular Officer
24 My Commission Expires: 1-9-2002